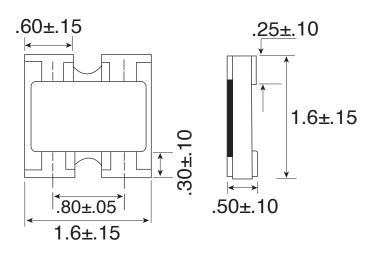


5% Thick Film Chip Resistor Array -Convex Terminal Series

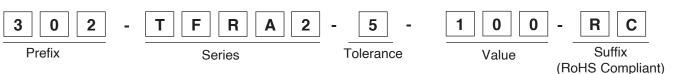
302-TFRA2 Series

Date Last Revised: 1/21/20

DIMENSIONS: mm



PART NUMBERING SYSTEM



SPECIFICATIONS:

Power Rating (Watts)	0.0625W(1/16W)
Max.Working Voltage	50V
Max.Overload Voltage	100V
Dielectric Withstanding Voltage	100V
Temperature Range	-55°C~+155°C
Ambient Temperature	70°C

NOTES :

· Nominal Resistance

Effective figures of nominal resistance shall be in accordance :

•E-24 and E-96 series for 1%

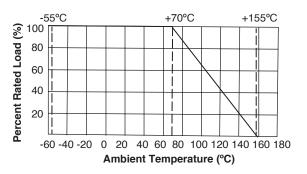
•E-24 series for 2% and 5%

•Resistance Range : $10\Omega \sim 1M\Omega$

RoHS Compliant

Available from Mouser Electronics 1-800-346-6873 / www.mouser.com

DERATING CURVE



5% Thick Film Chip Resistor Array-Convex Terminal

Characteristics	Limits	Test Methods (JIS C 5201-1)
Temperature coefficient	Refer to item 5	Natural resistance change per temp. degree centigrade. R2-R1
Short time overload	Resistance change rate is $\pm 5\%(2.0 \% + 0.1\Omega)$ Max. $\pm 1\%(1.0 \% + 0.1\Omega)$ Max.	Permanent resistance change after the application of a potential of 2.5 times RCWV for 5 seconds.
Insulation resistance	1,000M Ω or more	Apply 500V DC between protective coating and termination for 1 minute, then measure
Dielectric withstanding Voltage	No evidence of flashover mechanical damage,arcing or insulation break down	Clamped in the trough of a 90° metallic V-block and shall be tested at AC potential respectively specified in the table 1.for 60+10/-0 secs.
Terminal bending	Resistance change rate is $\pm(1.0\% + 0.05\Omega)$ Max	Twist of Test Board: Y/X=5/90mm for 10 seconds
*Solderability	95% coverage Min.	Test temperature of solder: 245 ± 3°C Dipping them solder: 2-3 seconds (Sub-clause 4.17)
Soldering temp. reference	Electrical characteristics shall be satisfied. Without distinct deformation in appearance. (95% coverage Min.)	Mave soldering condition: (2 cycles Max.) Pre-heat: 100 ~ 120 °C, 30 ± 5 sec. Suggestion solder temp.: 235 ~ 255 °C, 10 sec. (Max.) Peak temp.: 260°C Reflow soldering condition: (2 cycles Max.) Pre-heat: 150 ~ 180 °C, 90 ~ 120 sec. Suggestion solder temp.: 235 ~ 255 °C, 20 ~ 40 sec. Peak temp.: 260°C "Good of temp: 260°C "Bood of temp: 260°C Bood of temp: 260°C Bood of temp: 260°C Bood of temp

XC-600252

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Xicon:

 302-TFRA2-5-150K-RC
 302-TFRA2-5-10K-RC
 302-TFRA2-5-20-RC
 302-TFRA2-5-47K-RC
 302-TFRA2-5-2.4K-RC

 302-TFRA2-5-100K-RC
 302-TFRA2-5-4.7-RC
 302-TFRA2-5-4.7K-RC
 302-TFRA2-5-470K-RC
 302-TFRA2-5-470K-RC

 302-TFRA2-5-100-RC
 302-TFRA2-5-10-RC
 302-TFRA2-5-2.2K-RC
 302-TFRA2-5-200-RC
 302-TFRA2-5-5.1-RC

 302-TFRA2-5-15K-RC
 302-TFRA2-5-15-RC
 302-TFRA2-5-1K-RC
 302-TFRA2-5-5.1-RC